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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10044141	01/11/2002	257	723	3811	<i>Chen</i>

**APPLICANTS: Paek Jong Sik;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:
REPUBLIC OF KOREA 2001-02160 01/15/2001

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PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no			AMKOR-018A
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiners's initials			
TITLE : Semiconductor package with stacked dies			

U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
Assistant Examiner		Total Claims	Print Claim for O.G.
Primary Examiner		DRAWING	
Application Examiner		Sheets Drawg.	Figs. Drawg.
PREPARED FOR ISSUE		Print Fig.	
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